

**ASO ONLY (APPLICATION SPECIFIC ORDER)**

DO NOT  
SCALE FROM  
THIS PRINT

EDGE MOUNT	"A"	"B"	"C"	BODY	CONTACT
-EM2	.130[3.30]	.0670[1.702]	.058[1.47]	QTH-30-01-D-EM2-XX	T-1S42-01-X
*-EM3	.160[4.06]	.0980[2.489]	.088[2.24]	QTH-30-01-D-EM3-XX	T-1S42-02-X

\* = SEE NOTE 12

No OF POSITIONS

-030, -060, -090,  
\*\*-120, \*\*-150  
(PER ROW)

\*\*SEE NOTE 13

LEAD STYLE

-01: .1680[4.267]

— OPTION

-TY: TRAY PACKAGING

—EDGE MOUNT THICKNESS

-EM2: .064[1.63] +/- .004 PCB  
(USE QTH-30-01-D-EM2-XX &  
T-1S42-01-X)

-EM3:  
(USE QTH-30-01-D-EM3-XX &  
T-1542-02-X)

SEE NOTE 12

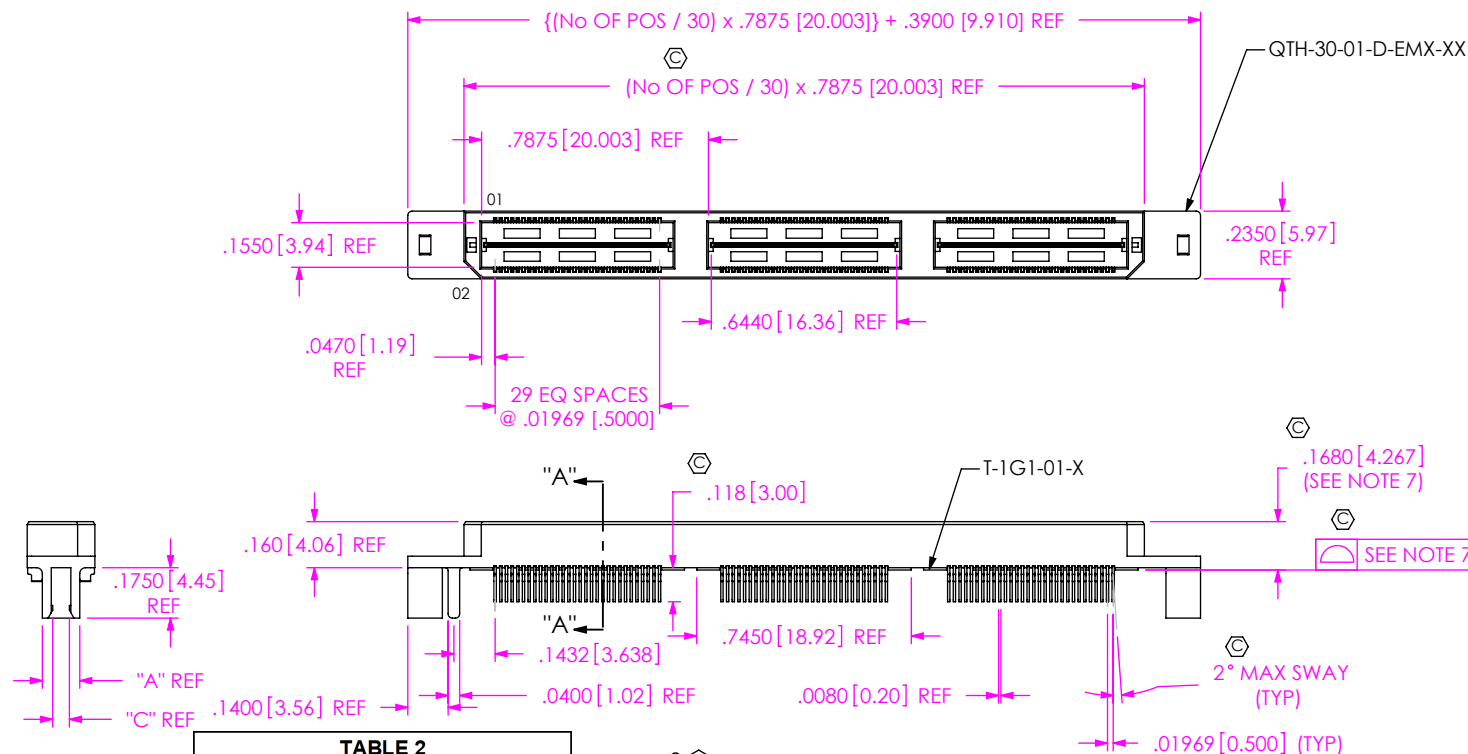
ROW SPECIFICATION

-D: DOUBLE  
(USE QTH-30-01-D-EMX-XX)

## PLATING SPECIFICATION



No OF BANKS

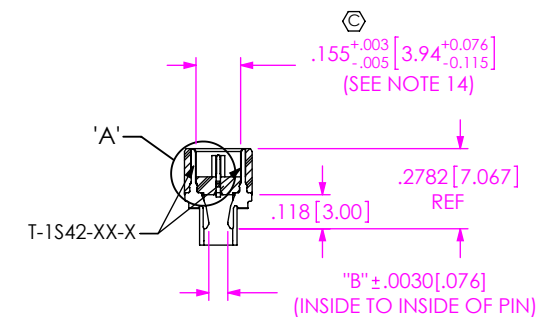
- F: 3µ" SELECTIVE GOLD IN CONTACT AREA,  
MATTE TIN ON TAILS  
(USE T-1G1-01-F) [SEE NOTE 8]
- L: 10µ" SELECTIVE GOLD IN CONTACT AREA  
MATTE TIN ON TAILS (USE T-1G1-01-L)
- H: 30µ" GOLD IN CONTACT AREA,  
3µ" GOLD ON TAIL (USE T-1G1-01-G)
- C: 50µ" GOLD IN CONTACT AREA,  
MATTE TIN ON TAILS (USE T-1G1-01-L)



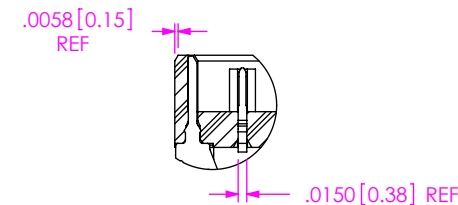
No OF POSITIONS	MAX BOW
-030, -060, -090	.004 [.10]
-120, -150	.006 [.15]

NOTES:

1.  REPRESENTS A CRITICAL DIMENSION.
2. BURR ALLOWANCE: .0015[.038] MAX.
3. MINIMUM PUSHOUT FORCE: 5 OZ.
4. MINIMUM GROUND PLANE RETENTION: 1 LB.
5. NOTE DELETED.
6. PARTS TO BE MOLDED TO POSITION.
7.  GROUND PLANE TO BE WITHIN .004[.10] COPLANARITY & MAX VARIANCE OF .002.
8. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING (TERMINAL),
9. NOTE DELETED.
10. BOARD THICKNESS TO BE MEASURED FROM SOLDER PAD TO SOLDER PAD.
11. SEE [www.samtec.com/processing/edgemnt\\_tectalk/index.htm](http://www.samtec.com/processing/edgemnt_tectalk/index.htm) FOR PROCESSING EDGE MOUNT PARTS TO BOARD.
12. -EM3 IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY.  
PLEASE CONTACT SAMTEC  
INTERCONNECT PROCESSING GROUP WITH ORDER INQUIRIES
13. FOR NEW APPLICATIONS REQUIRING THESE POSITIONS, PLEASE CONTACT SAMTEC  
INTERCONNECT PROCESSING GROUP.
14. ANY CHANGES SHOULD ALSO BE APPLIED TO QTH, QTE, QTS, BTH, BTE, AND BTS.
15. ORDERS WILL BE PACKAGED ACCORDING TO THE SAMTEC PACKAGING EFFICIENCY  
STANDARDS (SPES) FOUND ON [WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)



SECTION "A"-"A"



DETAIL 'A'  
SCALE 3 : 1

UNLESS OTHERWISE SPECIFIED,  
DIMENSIONS ARE IN INCHES.

TOLERANCES ARE:

DECIMALS

.XX:  $\pm .01$ [.3]

.XXX:  $\pm .005$ [.13]

.XXXX:  $\pm .0020$ [.051]

PROPRIETARY NOTE

**PROPRIETARY NOTE**  
THIS DOCUMENT CONTAINS INFORMATION  
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PURPOSE OTHER THAN THAT WHICH IT WAS  
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CONSENT OF SAMTEC, INC.

**MATERIAL:**

DO NOT SCALE DRAWING

SHEET SCALE: 1.5:1

INSULATOR: LCP, COLOR: BLACK  
TERMINAL & GROUND PLANE: PHOS BRONZE

DESCRIPTION:

.5mm HS EDGE MOUNT TERMINAL ASSEMBLY

DWG. NO.

QTH-XXX-01-X-D-EMX-XX

BY: DEAN P

4/20/2000

SHEET 1 OF 1

**samtec**

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